

## 1200V/20A RC-IGBT

### General Description

DOSEMI IGBT Power Discrete provides ultra low conduction loss as well as low switching loss. They are designed for the applications such as inductive cooking.

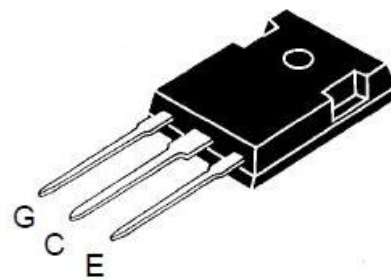
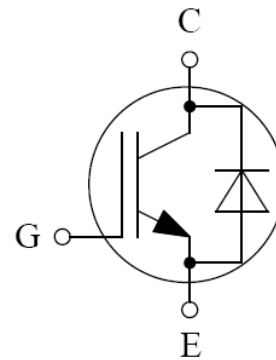
### Features

- Low  $V_{CE(sat)}$  Trench IGBT technology
- Low switching loss
- Maximum junction temperature 175°C
- Low inductance case
- $V_{CE(sat)}$  with positive temperature coefficient
- Fast & soft reverse recovery anti-parallel FWD
- Lead free package

### Typical Applications

- Inductive cooking

### Equivalent Circuit Schematic



TO-247

### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Description	Value	Unit
$V_{CES}$	Collector-Emitter Voltage	1200	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_c=25^\circ\text{C}$	40	A
	@ $T_c=100^\circ\text{C}$	20	A
$I_{CM}$	Pulsed Collector Current $t_p=1\text{ms}$	60	A
$P_D$	Maximum Power Dissipation @ $T_j=175^\circ\text{C}$	395	W

### Diode

Symbol	Description	Value	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage	1200	V
$I_F$	Diode Continuous Forward Current	20	A
$I_{FM}$	Diode Maximum Forward Current $t_p=1\text{ms}$	60	A

### Discrete

Symbol	Description	Values	Unit
$T_{jop}$	Operating Junction Temperature	-40 to +175	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-40 to +175	$^\circ\text{C}$
$T_S$	Soldering Temperature, 1.6mm from case for 10s	260	$^\circ\text{C}$
M	Mounting Torque, Screw M3	0.6	N.m

## IGBT Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=20\text{A}, V_{GE}=15\text{V}, T_j=25^\circ\text{C}$		1.75	1.95	V
		$I_C=20\text{A}, V_{GE}=15\text{V}, T_j=125^\circ\text{C}$		2.00		
		$I_C=20\text{A}, V_{GE}=15\text{V}, T_j=175^\circ\text{C}$		2.20		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=0.40\text{mA}, V_{CE}=V_{GE}, T_j=25^\circ\text{C}$	5.1	5.8	6.4	V
$I_{CES}$	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$			0.1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^\circ\text{C}$			100	nA
$R_{Gint}$	Internal Gate Resistance			0		$\Omega$
$t_{d(off)}$	Turn-Off Delay Time	$V_{CC}=600\text{V}, I_C=20\text{A}, R_G=15\Omega, V_{GE}=0/15\text{V}, T_j=25^\circ\text{C}$		345		ns
$t_f$	Fall Time			52		ns
$E_{off}$	Turn-Off Switching Loss			0.80		mJ
$t_{d(off)}$	Turn-Off Delay Time	$V_{CC}=600\text{V}, I_C=20\text{A}, R_G=15\Omega, V_{GE}=0/15\text{V}, T_j=175^\circ\text{C}$		426		ns
$t_f$	Fall Time			90		ns
$E_{off}$	Turn-Off Switching Loss			1.45		mJ

## Diode Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_F$	Diode Forward Voltage	$I_F=20\text{A}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$		1.70	1.90	V
		$I_F=20\text{A}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$		1.80		
		$I_F=20\text{A}, V_{GE}=0\text{V}, T_j=175^\circ\text{C}$		2.00		

## Discrete Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
$R_{thJC}$	Junction-to-Case (per IGBT)			0.380	K/W
$R_{thJA}$	Junction-to-Ambient		40		K/W

## RATING AND CHARACTERISTICS CURVES(RI20N1200TT)

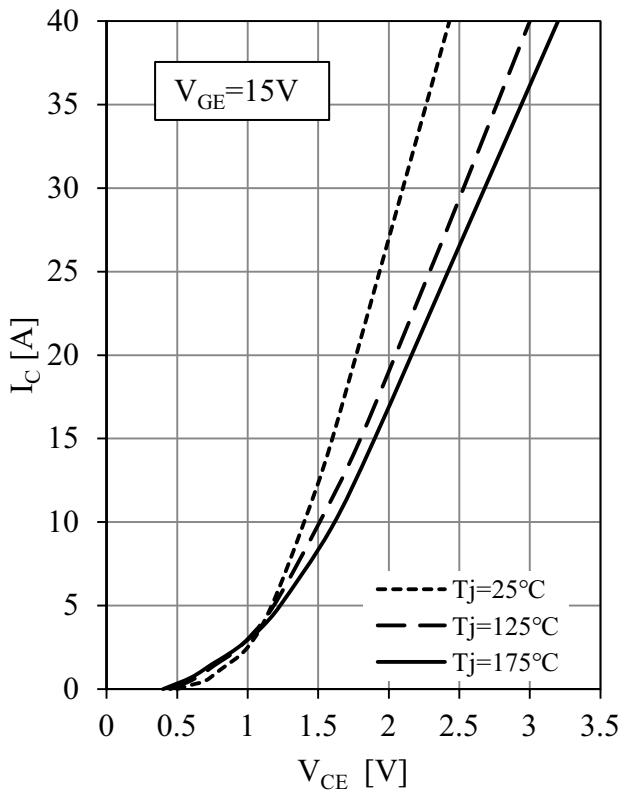


Fig 1. IGBT-inverter Output Characteristics

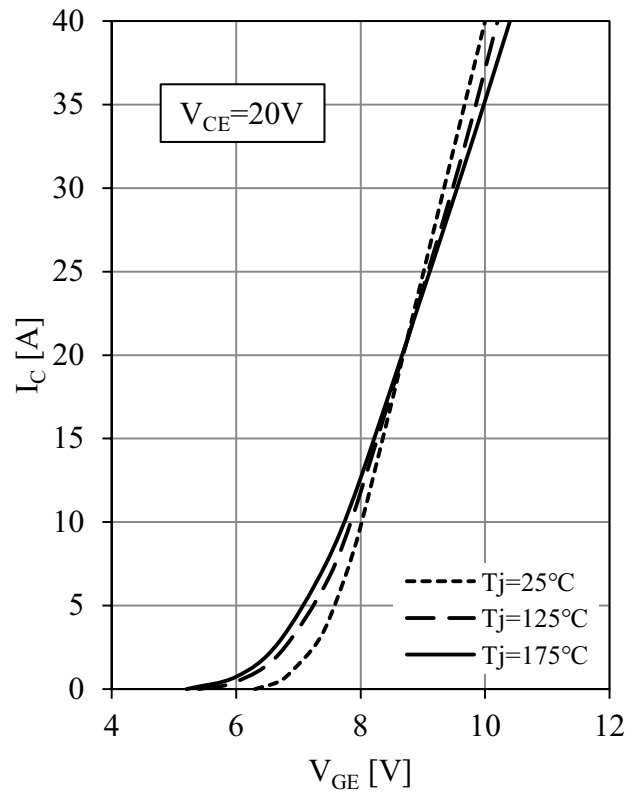


Fig 2. IGBT-inverter Transfer Characteristics

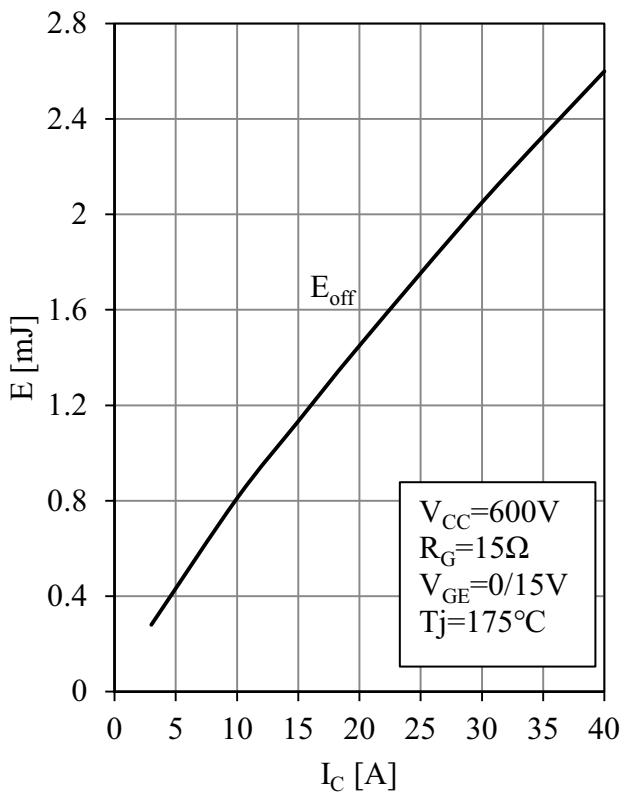


Fig 3. IGBT-inverter Switching Loss vs.  $I_C$

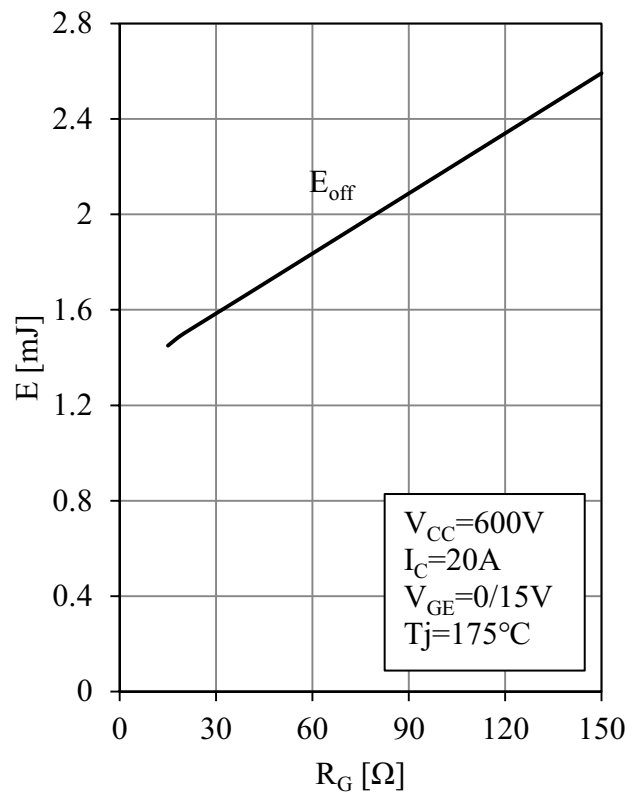


Fig 4. IGBT-inverter Switching Loss vs.  $R_G$

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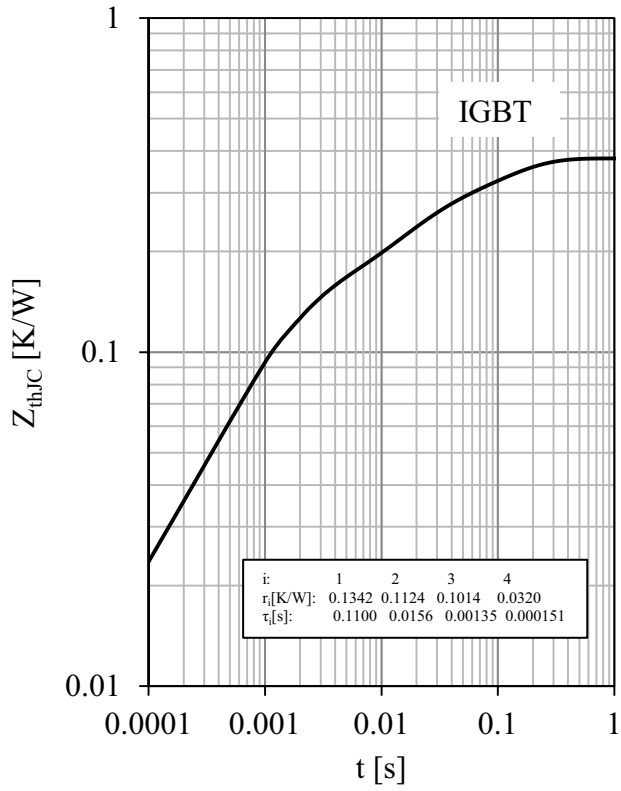


Fig 5. IGBT-inverter Transient Thermal Impedance

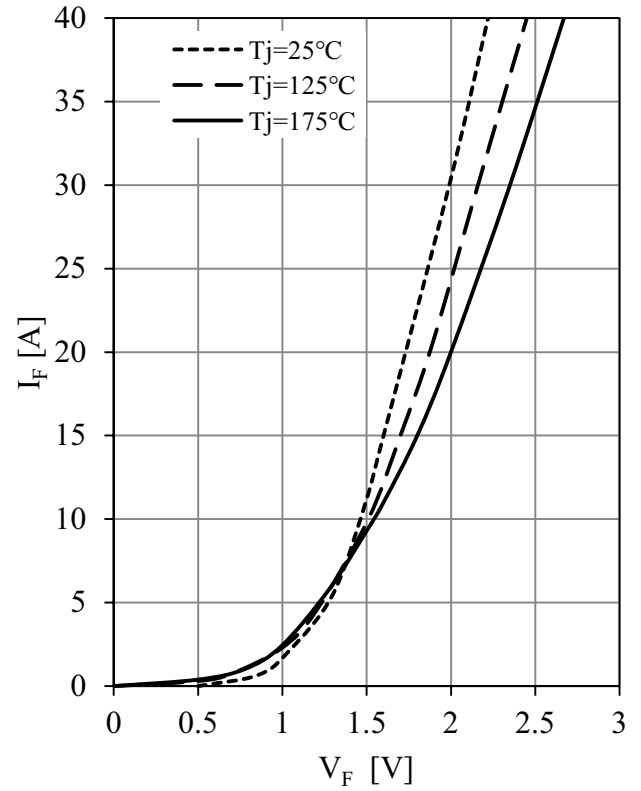
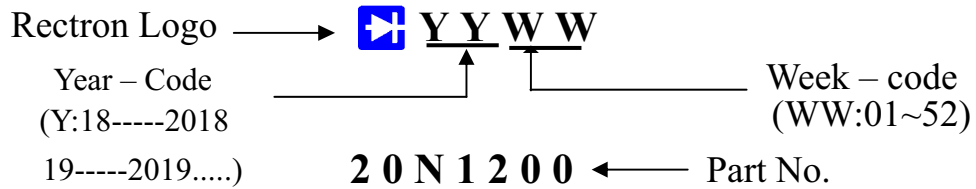


Fig 6. Diode-inverter Forward Characteristics



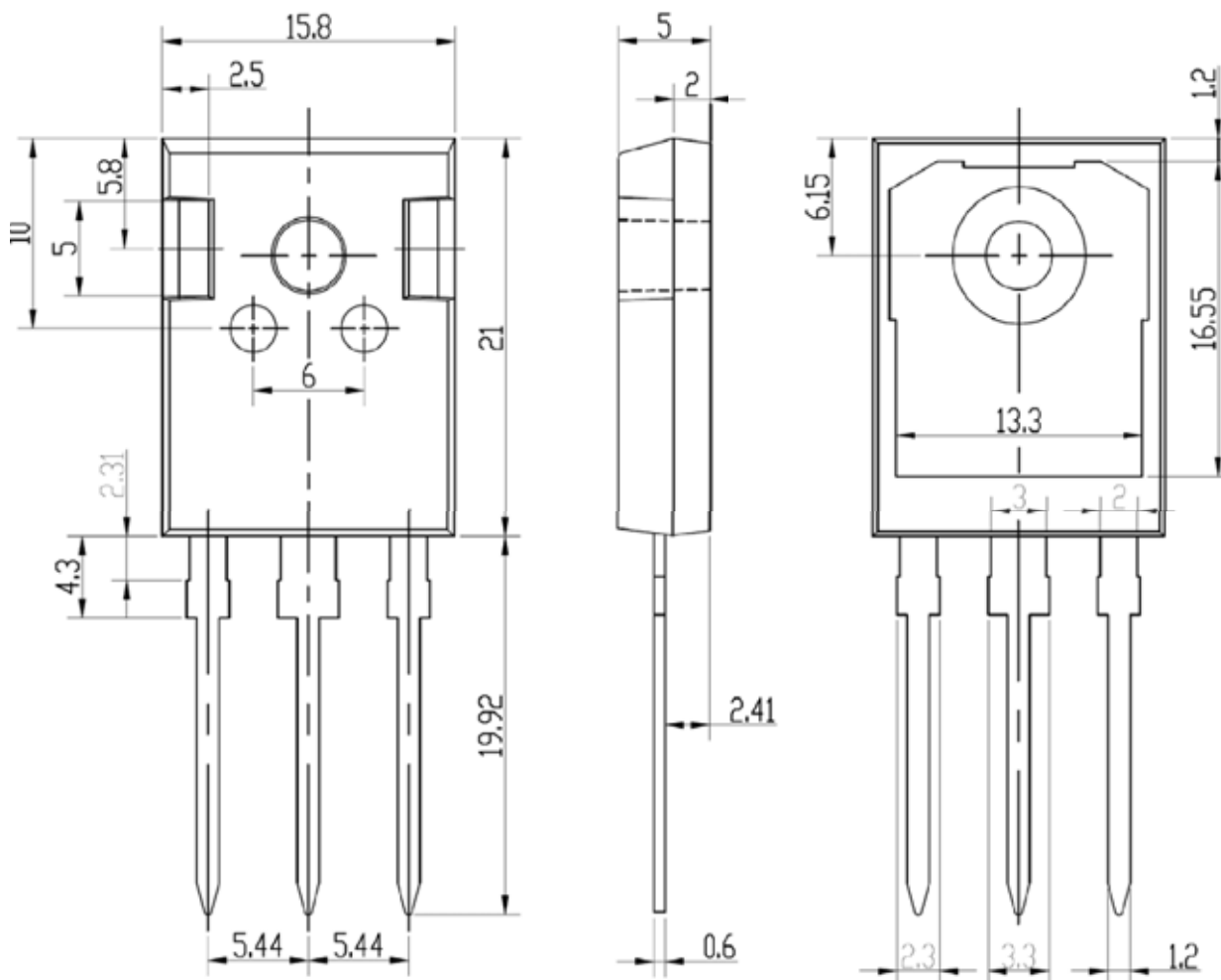
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## Marking on the body



# Package Dimensions

Dimensions in Millimeters



Package	Tube (pcs/tube)	Tube (pcs/inner box)	Tube (pcs/cartoon)	Tape&Reel (pcs/reel)	Tape&Reel (pcs/inner box)	Tape&Reel (pcs/cartoon)
DFN5x6/DFN3x3	100	10,000	100,000	2,500	5,000	40,000
DFN1006	—	—	—	10,000	10,000	400,000
SOP-8	100	10,000	100,000	4,000	4,000	20,000
TSSOP-8	100	32,000	128,000	3,000	6,000	48,000
SOT-23-3L	—	—	—	3,000	30,000	120,000
SOT-23-6L	—	—	—	3,000	30,000	120,000
SOT-23(6R)	—	—	—	3,000	30,000	120,000
SOT-363	—	—	—	3,000	30,000	120,000
SOT-523	—	—	—	3,000	30,000	120,000
SOT223	—	—	—	2,500	2,500	20,000
TO-220	50	1,000	5,000	—	—	—
TO-220F	50	1,000	10,000	—	—	—
TO-247	30	300	1,200	—	—	—
TO-251	80	4,000	40,000	—	—	—
TO-251S(4R)	80	4,000	40,000	—	—	—
TO-252-2L(4R)	80	4,000	40,000	2,500	2,500	25,000
TO-263-2L	50	1,000	10,000	800	800	8,000
TO-3P	30	300	3,000	—	—	—
TO-92	—	—	—	1,000(袋装)	10,000	100,000

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